

WHAT IS CLAIMED IS:

1. A storage medium comprising:

an information recording surface for recording information; and

5 an electronic-circuit mounting surface where electronic circuits are mounted at least on one portion.

2. The storage medium according to claim 1, wherein said storage medium has a front surface and a rear 10 surface,

and wherein said information recording surface is one of the front and rear surfaces, while said electronic-circuit mounting surface is the other one of the front and rear surfaces.

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3. The storage medium according to claim 1, wherein said electronic circuits include an electronic device mounted on an insulating substrate including a printed circuit board and a ceramic substrate.

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4. The storage medium according to claim 1, wherein said electronic circuits include a semiconductor circuit formed on a silicon wafer, a ceramic substrate or an insulating substrate.

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5. The storage medium according to claim 1, wherein

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said electronic circuits have a layered structure.

6. The storage medium according to claim 1, wherein
said electronic circuits have communication means for
5 communicating with outside.

7. The storage medium according to claim 6, wherein
said communication means includes a contact-type or non-
contact type contact.

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8. The storage medium according to claim 6, wherein
said communication means transmits energy superimposed
with a signal.

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9. The storage medium according to claim 1, wherein
said electronic circuit has power means for storing
energy supplied from a battery which generates energy
from inside, or from outside via a contact point,
optical means, wireless means or induction.

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10. The storage medium according to claim 1, wherein
said storage medium includes a magnetic disk, an optical
disk such as a CD or a DVD, a magneto-optical disk such
as an MO, an optical card, or a magneto-optical card.

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11. A method for manufacturing a storage medium where

electronic circuits are mounted, comprising:

 a step of manufacturing an information recording surface for recording information;

5 a step of manufacturing an electronic-circuit mounting surface including said electronic circuits at least on one portion; and

 a step of attaching said information recording surface to said electronic-circuit mounting surface.

10 12. The method for manufacturing a storage medium where electronic circuits are mounted, comprising:

 a step of manufacturing an information recording surface for recording information; and

15 a step of forming an electronic-circuit mounting surface including said electronic circuits at least on one portion, on the rear surface of said information recording surface.

13. A method for manufacturing a storage medium where
20 electronic circuits are mounted, comprising:

 a step of manufacturing an electronic-circuit mounting surface including said electronic circuits at least on one portion; and

25 a step of forming an information recording surface for recording information, on the rear surface of said electronic-circuit mounting surface.

14. The method according to claim 11, wherein said step of manufacturing said information recording surface includes:

5 a step of injecting a base;
 a step of forming a reflection film on said base;
and
 a step of coating said reflection film with a protective film.

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15. The method according to claim 11, wherein said step of manufacturing said electronic-circuit mounting surface includes;

15 a step of mounting the electronic circuit; and
 a step of coating or forming a protective film or layer over said electronic circuit.

16. The method according to claim 15, wherein said step of mounting said electronic circuit includes:

20 a step of forming a conductive wiring;
 a step of mounting an insulating substrate including a printed circuit board and a ceramic substrate, where an electronic device is mounted, or a silicon wafer, a ceramic substrate or an insulating substrate, where a semiconductor circuit is formed.

17. The method according to claim 15, wherein said step of mounting said electronic circuit includes;

a step of forming a silicon wafer, a ceramic substrate or an insulating substrate; and

5 a step of forming a semiconductor circuit on said silicon wafer, ceramic substrate or insulating substrate.

18. The method according to claim 12, wherein said step of manufacturing said information recording surface includes:

a step of injecting a base;

a step of forming a reflection film on said base;

and

15 a step of coating said reflection film with a protective film.

19. The method according to claim 12, wherein said step of manufacturing said electronic-circuit mounting surface includes;

20 a step of mounting the electronic circuit; and

a step of coating or forming a protective film or layer over said electronic circuit.

20. The method according to claim 19, wherein said

25 step of mounting said electronic circuit includes:

a step of forming a conductive wiring:

a step of mounting an insulating substrate including a printed circuit board and a ceramic substrate, where an electronic device is mounted, or a silicon wafer, a ceramic substrate or an insulating substrate, where a semiconductor circuit is formed.

21. The method according to claim 19, wherein said step of mounting said electronic circuit includes;

10 a step of forming a silicon wafer, a ceramic substrate or an insulating substrate; and

a step of forming a semiconductor circuit on said silicon wafer, ceramic substrate or insulating substrate.

22. The method according to claim 13, wherein said

15 step of manufacturing said information recording surface includes:

a step of injecting a base;

a step of forming a reflection film on said base;

and

20 a step of coating said reflection film with a protective film.

23. The method according to claim 13, wherein said

step of manufacturing said electronic-circuit mounting
25 surface includes;

a step of mounting the electronic circuit; and

a step of coating or forming a protective film or layer over said electronic circuit.

24. The method according to claim 23, wherein said
5 step of mounting said electronic circuit includes:

a step of forming a conductive wiring:

a step of mounting an insulating substrate
including a printed circuit board and a ceramic
substrate, where an electronic device is mounted, or a
10 silicon wafer, a ceramic substrate or an insulating
substrate, where a semiconductor circuit is formed.

25. The method according to claim 23, wherein said
step of mounting said electronic circuit includes;

15 a step of forming a silicon wafer, a ceramic
substrate or an insulating substrate; and

a step of forming a semiconductor circuit on said
silicon wafer, ceramic substrate or insulating substrate.

20 26. The method according to claim 11, wherein said
storage medium includes a magnetic disk, a magnetic card,
an optical disk such as a CD or a DVD, a magneto-optical
disk such as an MO, an optical card or a magneto-optical
card.